## BST-21503A 150g LED BGA SMD PGA



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 $\square\square\square$ BST-21503A

ППП60°С

□□□150g / pc

## PRODUCT DISPLAY



## PRODUCT DETAILS

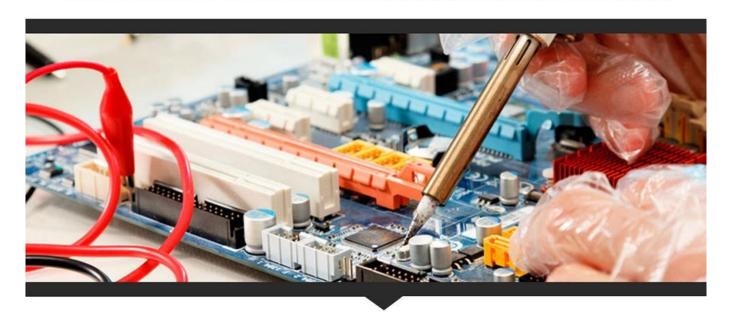




Name: Soldering Paste Model: BST-21503A

Size: Φ80\*45mm Weight: 100g

Composition: Solder powder, resin Melting point:60°C





- Stable performance, Not volatile, long life cycle, the amount of province;
- Non-toxic non-irritating odor, the use of safe and reliable;
- ▲ The IC and PCB are not corrosive
- Its boiling point is only slightly higher than the melting point of solder.

**Features**: Solder melting at the time of soldering begins to boil endothermic vaporization, which can be maintained at this temperature using IC and PCB temperatures. In the demolition of the chip with a lot of solder paste, it melts fast, you can flow to the BGA chip below. Rosin is solid without solder paste convenient.









